

**AMENDMENTS TO THE SPECIFICATION:**

Please replace the title with the following amended title:

**"PACKAGE FOR OPTICAL SEMICONDUCTOR PACKAGE"**

Please replace the paragraph beginning on page 16, line 5, and ending on page 16, line 13, with the following amended paragraph:

The internal configuration of the can package 1 will next be explained with reference to Fig. 5 to Fig. 48 7. Fig. 5 is a perspective view illustrating the can package 1 in a state in which the cap 13 is detached. Fig. 6 is a plane view of the can package 1. Fig. 7 illustrates the arrangement relationship and the like among the stem, the pins, and the pedestal. For convenience of explanation, Fig. 6 slightly differs from Figs. 3A and 3B, Fig. 5, and Fig. 7 in positions at which the bias feed pins 44a and 44b, the monitor signal pin 43, and the like are arranged.

Please replace the following Abstract with the amended Abstract on the following page:

Includes a stem (10) with a hole (74), a dielectric (77) sealed into the hole (74) of the stem (10) and including a pair of pin insertion holes (80a, 80b), and a pair of high frequency signal pins (41a, 41b) that penetrate and fit into the pair of pin insertion holes (80a, 80b) of the dielectric (77), and constituting differential lines connected to an optical semiconductor element (LD) (40).